



GAU 2827

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THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Salam Akram § Group Art Unit: 2827  
Serial No.: 09/853,111 §  
Filed: May 10, 2001 §  
For: Mounting Multiple Semiconductor § Atty. Dkt. No.: MCT.0012D1US  
Dies In A Package § (97-014)  
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Commissioner for Patents  
Washington DC 20231

**REPLY TO PAPER NO. 2**

Sir:

In response to the office action mailed January 6, 2002, please amend the above-referenced patent application as follows:

**In the Drawings:**

Please amend the drawings as indicated in red on the attached figures.

**In the Title:**

Please amend the title to read:

"Method of Fabricating Mounted Multiple Semiconductor Dies in a Package".

**In the Claims:**

Please amend claim 15 as follows:

15. (Amended) A method for mounting multiple semiconductor dies on a single leadframe, comprising:  
stacking at least two semiconductor dies having substantially the same rectangular dimensions on top of one another; and  
wire bonding each of the semiconductor dies to the leadframe.

Date of Deposit: 2/1/02

I hereby certify under 37 CFR 1.8(a) that this correspondence is being deposited with the United States Postal Service as **first class mail** with sufficient postage on the date indicated above and is addressed to the Commissioner for Patents, Washington DC 20231.

Lisa O'Sullivan